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PATENT  
PD-8811

A/W

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of )  
Michio Asahina )  
Serial No.: 07/151,361 )  
Filed: February 2, 1988 )  
For: SEMICONDUCTOR DEVICE )

#8  
P.W.  
1-3-89

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner  
Patent and Trademark Office  
Washington, D.C. 20231

Dear Sir:

Submitted herewith is a copy of U.S. Patent No.  
4,182,781, which has come to applicant's attention.

This patent discloses a method in which a bump  
electrode forming part of a metal plating layer is formed as  
one part of the wiring. The method disclosed in this patent  
corresponds to that illustrated in Figures 3 of the present  
application, which are described in the specification as  
relating to one conventional manufacturing procedure.

It is asked that this reference be made of record and  
substantively considered.

December 15, 1988  
Date

Respectfully submitted, APPLICATION BRANCH

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Commissioner of Patents and Trademarks, Wash-  
ington, D.C. 20231, on Dec. 15, 1988  
(Date of Deposit)

William K. Konrad, R.N. 28,868

Name of Applicant, assignee, or Registered Rep.

Signature

Date